

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	161261	(solid electrolytic chip die type) with (capacitor capacitance)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 15:22
L2	47291	(lead terminal pad electrode leaframe) with 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 15:23
L3	8244	anode and cathode and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 15:23
L4	1469	(package packaging packaged encase encapsulant encapsulating encapsulation encapsulated) and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 15:24
L5	633	(adhesion adhesion ag silver) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 15:26
L6	1087	(adhesion adhesion ag silver paste conductive) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 15:25
L7	840	(adhesion adhesion ag silver au gold cu copper) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 15:26
L8	877	(adhesion adhesion ag silver au gold cu copper pd palladium) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 15:26

L9	951	(adhesive adhesion ag silver au gold cu copper pd palladium) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 15:27
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